

"Half-Bridge" IGBT INT-A-PAK, (Standard Speed IGBT), 100 A



INT-A-PAK

PRIMARY CHARACTERISTICS				
V _{CES}	600 V			
I _C DC	220 A			
V _{CE(on)} at 100 A, 25 °C	1.11 V			
Speed	DC to 1 kHz			
Package	INT-A-PAK			
Circuit configuration	Half bridge			

FEATURES

- Standard speed PT IGBT technology
- · Optimized for hard switching speed
- FRED Pt® antiparallel diodes with fast recovery
- Very low conduction losses
- Al₂O₃ DBC
- UL approved file E78996
- Designed for industrial level
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

BENEFITS

- Optimized for high current inverter stages (AC TIG welding machines)
- Direct mounting to heatsink
- Very low junction to case thermal resistance
- Low EMI

ABSOLUTE MAXIMUM RATINGS					
PARAMETER	SYMBOL	SYMBOL TEST CONDITIONS		UNITS	
Collector to emitter voltage	V _{CES}		600	V	
Continuous collector current		T _C = 25 °C	220		
Continuous collector current	I _C	T _C = 130 °C	100	Α	
Pulsed collector current	I _{CM}		440	A	
Peak switching current	I _{LM}		440		
Gate to emitter voltage	V _{GE}		± 20	V	
RMS isolation voltage	V _{ISOL}	Any terminal to case, t = 1 min	2500	v	
Maximum nauror dissination	P _D	T _C = 25 °C	780	W	
Maximum power dissipation		T _C = 100 °C	312]	
Operating junction temperature range	TJ		-40 to +150	°C	
Storage temperature range	T _{Stg}		-40 to +125		

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Collector to emitter breakdown voltage	V _{BR(CES)}	$V_{GE} = 0 \text{ V}, I_{C} = 1 \text{ mA}$	600	-	-		
		V _{GE} = 15 V, I _C = 100 A	-	1.11	1.28	v	
Collector to emitter voltage	V _{CE(on)}	I _C = 200 A	-	1.39	-		
		V _{GE} = 15 V, I _C = 100 A, T _J = 125 °C	-	1.08	1.22		
Gate threshold voltage	V _{GE(th)}	I _C = 0.25 mA	3	-	6		
Callestanta ancittan la la cara a comunit	I _{CES}	V _{GE} = 0 V, V _{CE} = 600 V	-	-	1	mA	
Collector to emitter leakage current		V _{GE} = 0 V, V _{CE} = 600 V, T _J = 125 °C	-	-	10		
Diada famuard valtage drep	V	I _C = 100 A, V _{GE} = 0 V	-	1.44	1.96	V	
Diode forward voltage drop	V_{FM}	I _C = 100 A, V _{GE} = 0 V, T _J = 125 °C	-	1.25	1.54	\ \ \	
Gate to emitter leakage current	I _{GES}	V _{GE} = ± 20 V	-	-	± 250	nA	



SWITCHING CHARACTERISTICS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Total gate charge	Qg	I _C = 100 A	-	640	700	
Gate to emitter charge	Q_ge	V _{CC} = 400 V	-	108	120	nC
Gate to collector charge	Q_{gc}	V _{GE} = 15 V	-	230	300	
Rise time	t _r	1. 100 A	-	0.45	-	
Fall time	t _f	$I_{C} = 100 \text{ A}$ $V_{CC} = 480 \text{ V}$	-	1.0	-	μs
Turn-on switching energy	E _{on}	V _{GE} = 15 V	-	4	6	
Turn-off switching energy	E _{off}	$R_g = 15 \Omega$	-	23	29	
Total switching energy	E _{ts}	T _J = 25 °C	-	27	35	mJ
Turn-on switching energy	E _{on}	I _C = 100 A, V _{CC} = 480 V	-	6	12	
Turn-off switching energy	E _{off}	$V_{GE} = 15 \text{ V}, R_{g} = 15 \Omega$	-	35	40	
Total switching energy	E _{ts}	T _J = 125 °C	-	41	52	
Input capacitance	C _{ies}	V _{GE} = 0 V	-	16 250	-	
Output capacitance	Coes	V _{CC} = 30 V	-	1040	-	рF
Reverse transfer capacitance	C _{res}	f = 1.0 MHz	-	190	-	
Diode reverse recovery time	t _{rr}	I _E = 50 A	-	91	155	ns
Diode peak reverse current	I _{rr}	dl _F /dt = 200 A/μs	-	10.6	15	Α
Diode recovery charge	Q _{rr}	$V_{rr} = 200 \text{ V}$	-	500	900	nC
Diode reverse recovery time	t _{rr}	I _F = 50 A	-	180	344	ns
Diode peak reverse current	I _{rr}	dl _F /dt = 200 A/μs	-	17	20.5	Α
Diode recovery charge	Q _{rr}	V _{rr} = 200 V, T _J = 125 °C	-	1633	2315	nC

THERMAL AND MECHANICAL SPECIFICATIONS							
PARAMETER		SYMBOL	MIN.	TYP.	MAX.	UNITS	
Operating junction temperature range		T _J	-40	-	150	- °C	
Storage temperature range		T _{Stg}	-40	-	125		
Junction to case	per switch	R _{thJC}	-	-	0.16	°C/W	
	per diode		-	-	0.48		
Case to sink per module		R _{thCS}	-	0.1	ı		
Mounting torque	case to heatsink		-	-	4	Nm	
	case to terminal 1, 2, 3		-	-	3		
Weight			-	185	-	g	

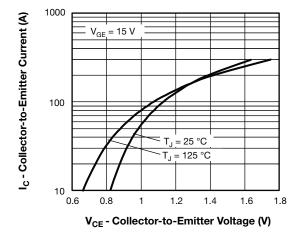


Fig. 1 - Typical Output Characteristics

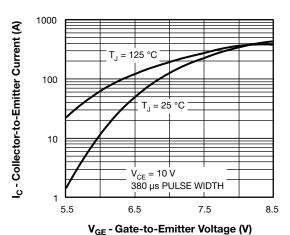


Fig. 2 - Typical Transfer Characteristics



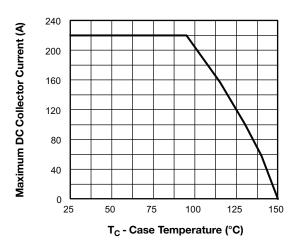


Fig. 3 - Maximum Collector Current vs. Case Temperature

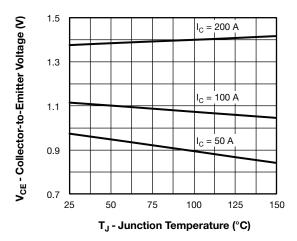


Fig. 4 - Typical Collector to Emitter Voltage vs. Junction Temperature

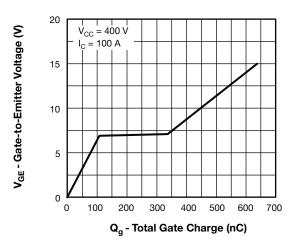


Fig. 5 - Typical Gate Charge vs. Gate to Emitter Voltage

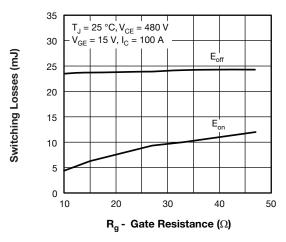


Fig. 6 - Typical Switching Losses vs. Gate Resistance

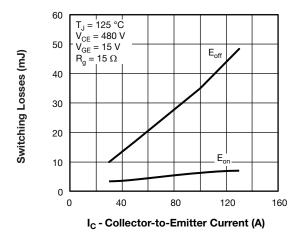


Fig. 7 - Typical Switching Losses vs. Collector to Emitter Current

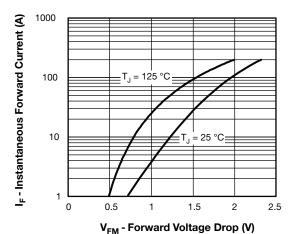
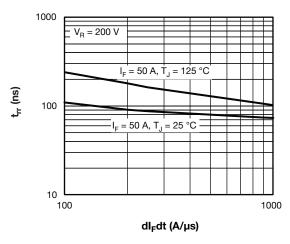


Fig. 8 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current





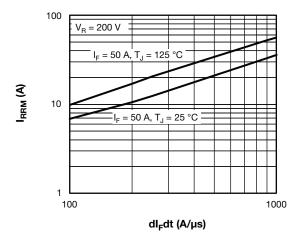


Fig. 9 - Typical Reverse Recovery Time vs. dl_F/dt

Fig. 10 - Typical Reverse Recovery Current vs. dl_F/dt

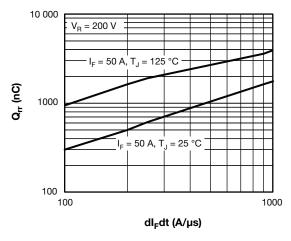
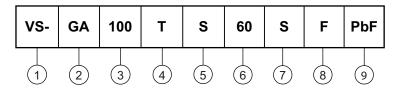


Fig. 11 - Typical Stored Charge vs. dl_F/dt

ORDERING INFORMATION TABLE

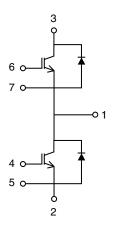
Device code



- 1 Vishay Semiconductors product
- 2 Essential part number IGBT modules
- 3 Current rating (100 = 100 A)
- Circuit configuration (T = half bridge)
- 5 INT-A-PAK
- 6 Voltage code (60 = 600 V)
- 7 Speed / type (S = standard speed IGBT)
- 8 Diode type
- 9 None = standard production; PbF = lead (Pb)-free



CIRCUIT CONFIGURATION

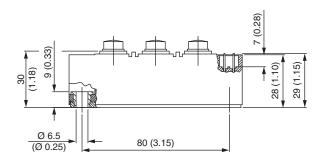


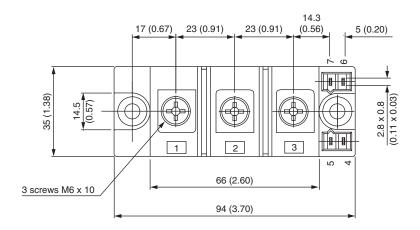
LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95173			

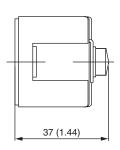


INT-A-PAK IGBT

DIMENSIONS in millimeters (inches)









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